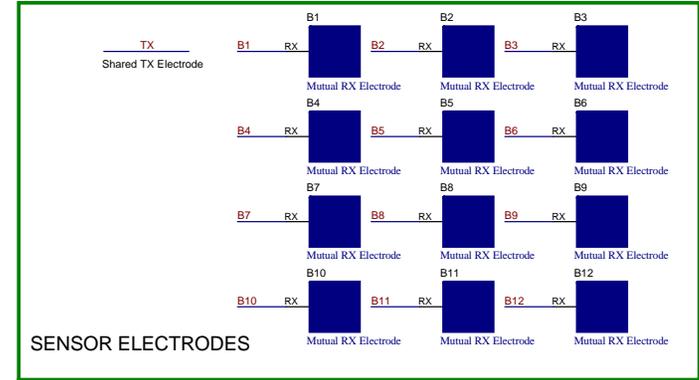
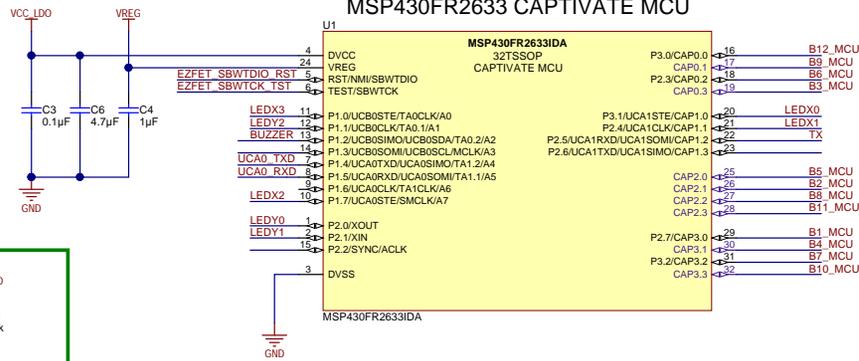
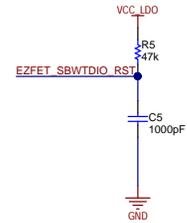


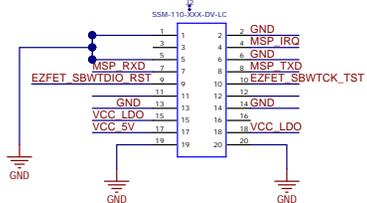
# TIDM-1021 Schematic



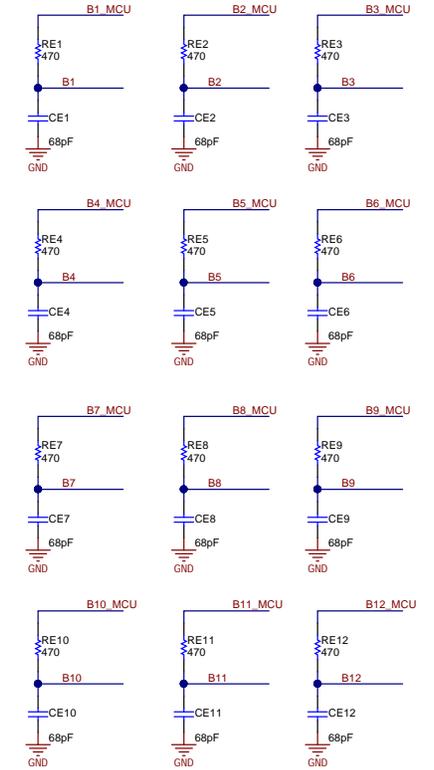
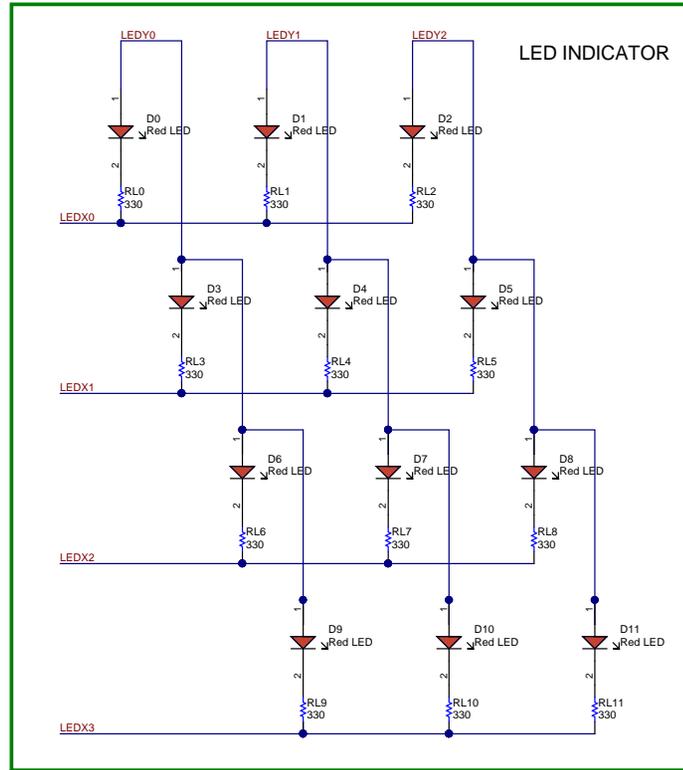
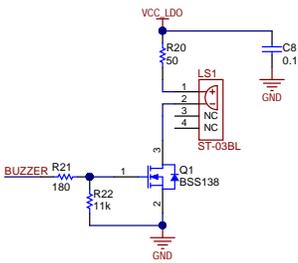
## MSP430FR2633 RESET



## PROGRAMMER EDGE CONNECTOR



## BUZZER INDICATOR



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Orderable: Not Orderable	Designed for: Public Release	Mod. Date: 7/21/2018
TID #: TIDM-1021	Project Title: TIDM-1021	
Number: TIDM-1021	Rev: 1	Sheet Title: TIDM-1021
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By: Yiding Luo	File: Schematic_SchDoc	Size: B
Engineer: Yiding Luo	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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